

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT54 (TO-92) plastic package. This "series D" triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers and logic ICs including microcontrollers.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- Direct gate triggering from low power drivers and logic ICs
- High commutation capability with very sensitive gate
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only
- Very sensitive gate for easy logic level triggering

## 3. Applications

- Low power motor controls
- Small inductive loads e.g. solenoids, door locks, water valves
- Small loads in large white goods

## 4. Quick reference data

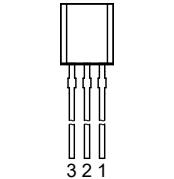
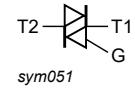
Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	-	800	V
$I_T(\text{RMS})$	RMS on-state current	full sine wave; $T_{\text{lead}} \leq 70^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>	-	-	0.8	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 20 \text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>	-	-	9	A
		full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 16.7 \text{ ms}$	-	-	9.9	A
$T_j$	junction temperature		-	-	125	$^\circ\text{C}$
<b>Static characteristics</b>						
$I_{GT}$	gate trigger current	$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2+ G+; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>	0.25	-	5	mA
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2+ G-; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>	0.25	-	5	mA

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2- G-; $T_j = 25^\circ\text{C}$ ; Fig. 7		0.25	-	5	mA
$I_H$	holding current	$V_D = 12 \text{ V}$ ; $T_j = 25^\circ\text{C}$ ; Fig. 9		-	-	10	mA
$V_T$	on-state voltage	$I_T = 0.85 \text{ A}$ ; $T_j = 25^\circ\text{C}$ ; Fig. 10		-	1.35	1.6	V
<b>Dynamic characteristics</b>							
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}$ ; $T_j = 125^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit		200	-	-	V/ $\mu\text{s}$
$dI_{com}/dt$	rate of change of commutating current	$V_D = 400 \text{ V}$ ; $T_j = 125^\circ\text{C}$ ; $I_{T(RMS)} = 0.8 \text{ A}$ ; $dV_{com}/dt = 10 \text{ V}/\mu\text{s}$ ; gate open circuit		0.5	-	-	A/ms

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T2	main terminal 2		
2	G	gate		
3	T1	main terminal 1	 <b>TO-92 (SOT54)</b>	 sym051

## 6. Ordering information

Table 3. Ordering information

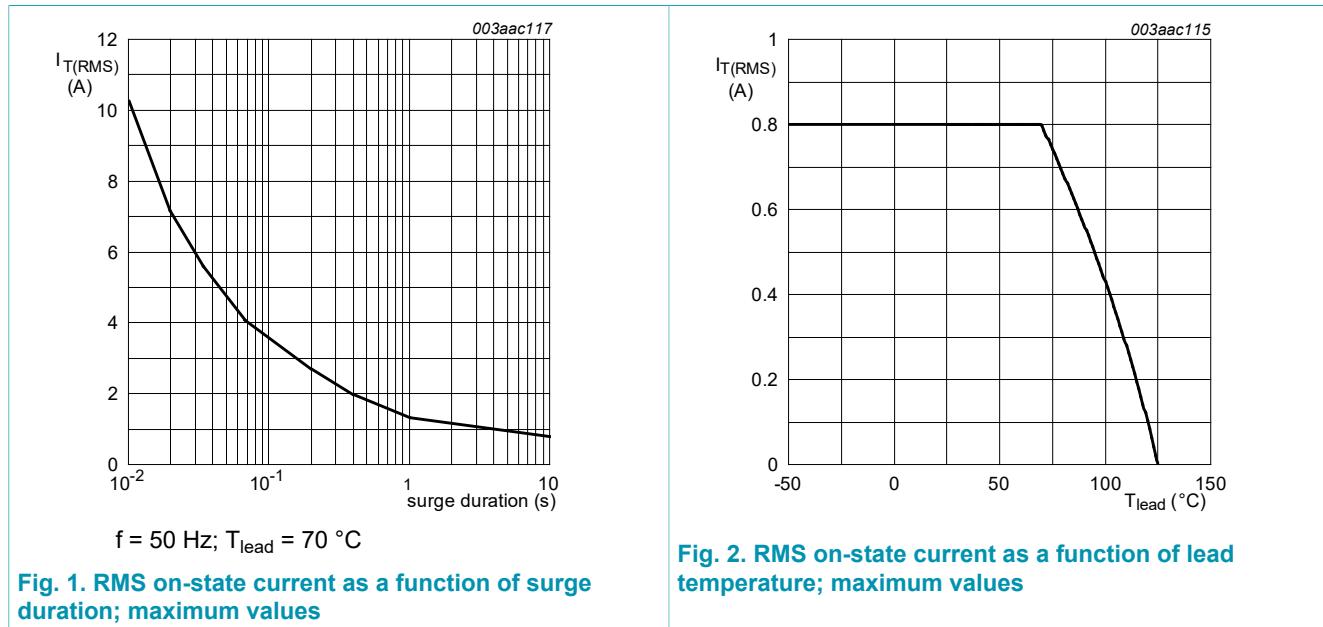
Type number	Package		
	Name	Description	Version
T2008-800D	TO-92	plastic single-ended leaded (through hole) package; 3 leads	SOT54

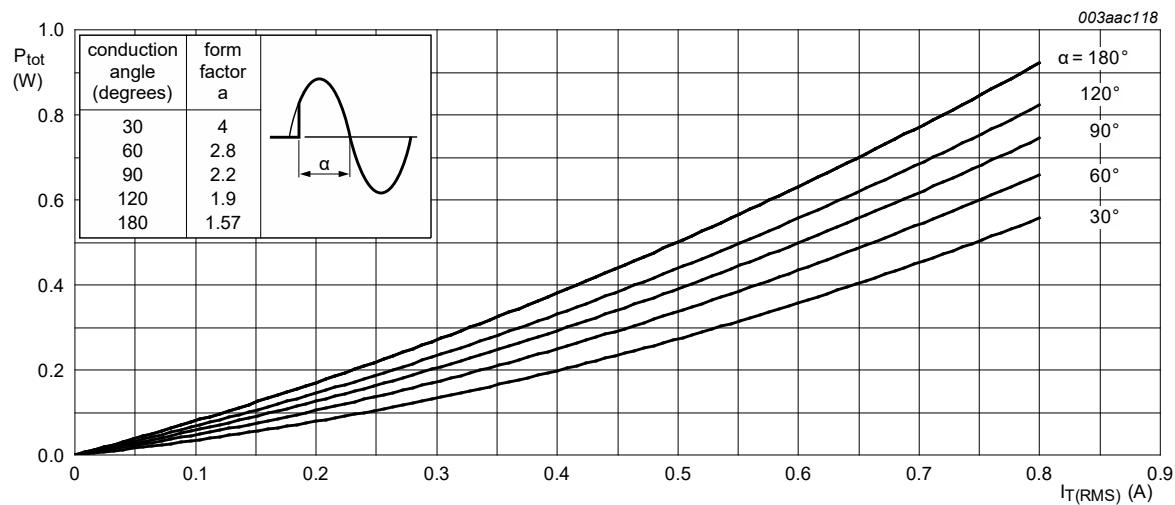
## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage			-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{lead} \leq 70^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	0.8	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(init)} = 25^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		-	9	A
		full sine wave; $T_{j(init)} = 25^\circ\text{C}$ ; $t_p = 16.7\text{ ms}$		-	9.9	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; SIN		-	0.41	$\text{A}^2\text{s}$
$dI_T/dt$	rate of rise of on-state current	$I_G = 20\text{ mA}$		-	100	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current			-	1	A
$P_{GM}$	peak gate power			-	2	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.1	W
$T_{stg}$	storage temperature			-40	150	$^\circ\text{C}$
$T_j$	junction temperature			-	125	$^\circ\text{C}$





$\alpha$  = conduction angle  
 $a$  = form factor =  $I_{T(RMS)} / I_{T(AV)}$

Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

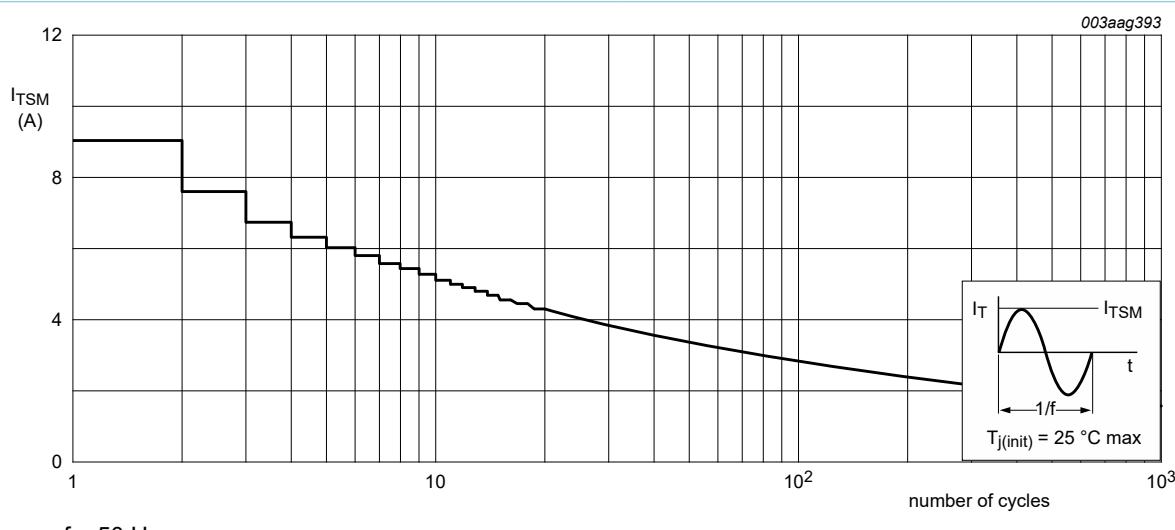


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-lead})}$	thermal resistance from junction to lead	full cycle; Fig. 6		-	-	60	K/W
$R_{th(j\text{-a})}$	thermal resistance from junction to ambient free air	printed circuit board mounted: lead length = 4 mm		-	150	-	K/W

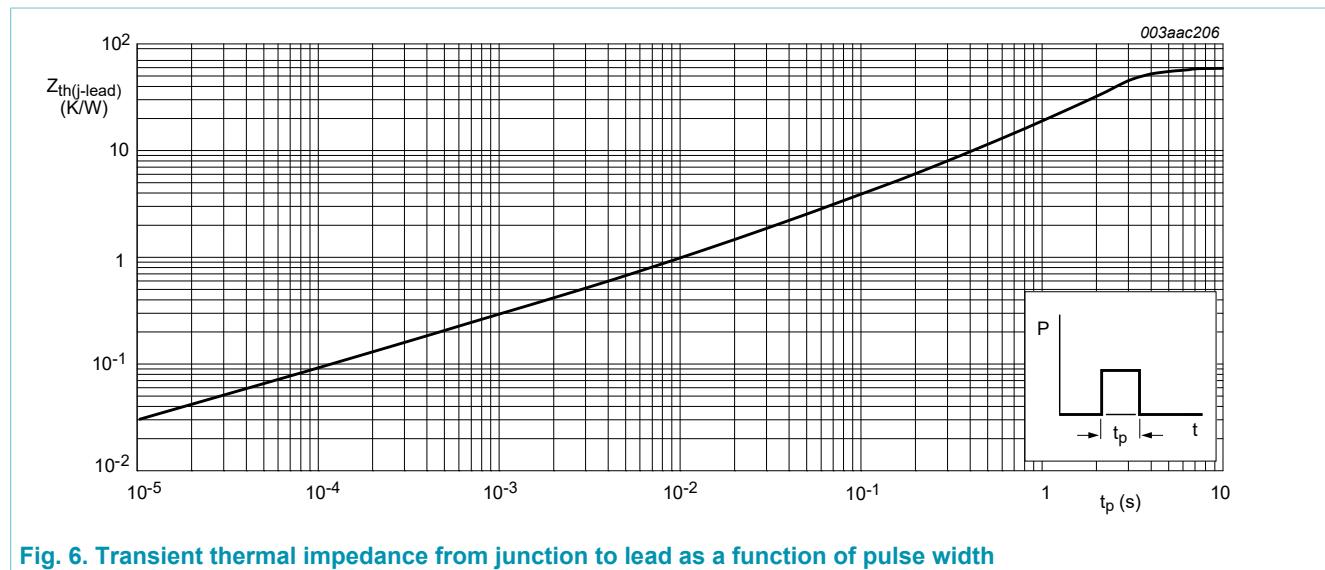


Fig. 6. Transient thermal impedance from junction to lead as a function of pulse width

## 9. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
<b>Static characteristics</b>							
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		0.25	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		0.25	-	5	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>		0.25	-	5	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	10	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	20	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>		-	-	10	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 9</a>		-	-	10	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 0.85 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 10</a>		-	1.35	1.6	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 11</a>		-	0.9	1.5	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 125 °C; <a href="#">Fig. 11</a>		0.2	0.3	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 125 °C		-	0.1	0.5	mA
<b>Dynamic characteristics</b>							
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 536 V; T <sub>j</sub> = 125 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit		200	-	-	V/μs
dI <sub>com</sub> /dt	rate of change of commutating current	V <sub>D</sub> = 400 V; T <sub>j</sub> = 125 °C; I <sub>T(RMS)</sub> = 0.8 A; dV <sub>com</sub> /dt = 10 V/μs; gate open circuit		0.5	-	-	A/ms

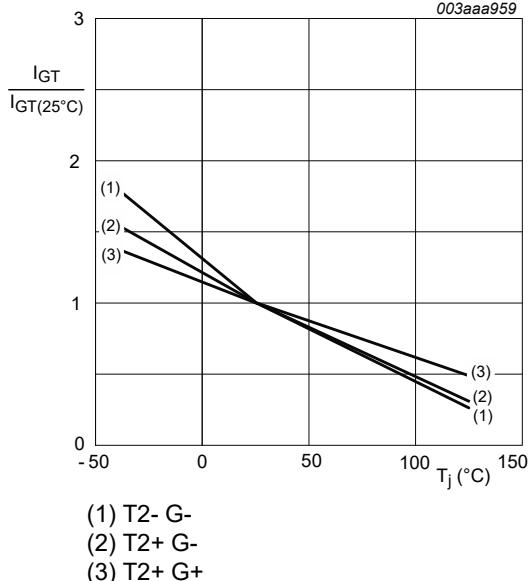


Fig. 7. Normalized gate trigger current as a function of junction temperature

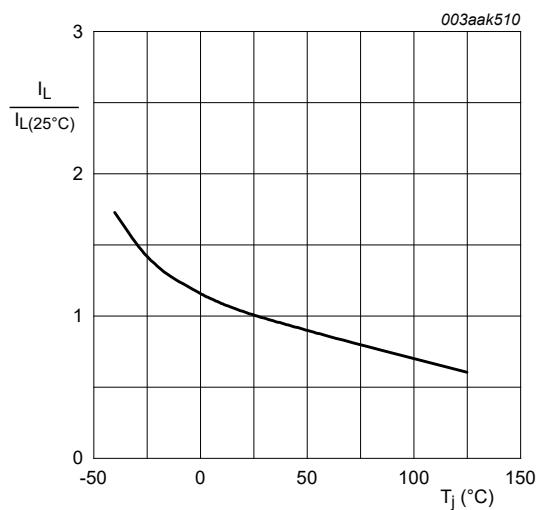


Fig. 8. Normalized latching current as a function of junction temperature

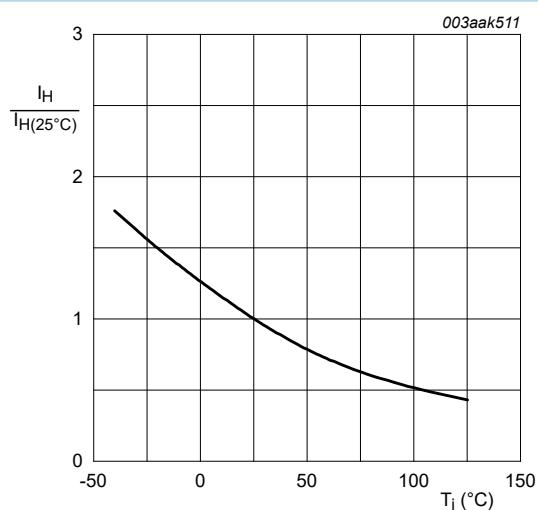


Fig. 9. Normalized holding current as a function of junction temperature

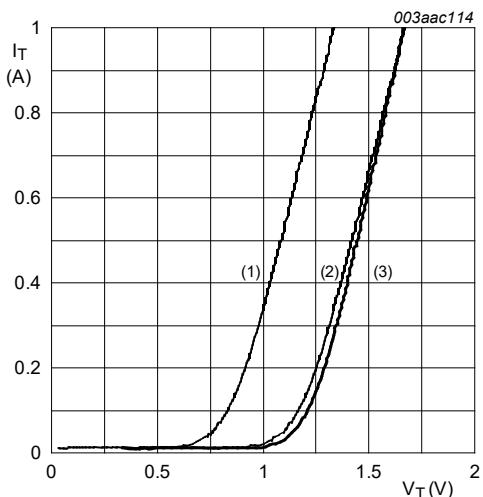
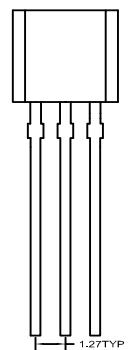


Fig. 10. On-state current as a function of on-state voltage  
 $V_O = 0.835 \text{ V}; R_s = 0.50 \Omega$   
(1)  $T_j = 125 \text{ }^{\circ}\text{C}$ ; typical values  
(2)  $T_j = 125 \text{ }^{\circ}\text{C}$ ; maximum values  
(3)  $T_j = 25 \text{ }^{\circ}\text{C}$ ; maximum values

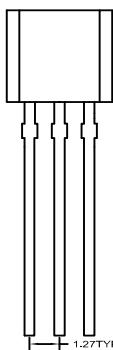
Fig. 10. On-state current as a function of on-state voltage

## 10. Package outline

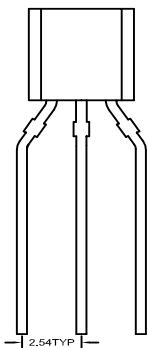
SOT54 PACKAGE OUTLINE



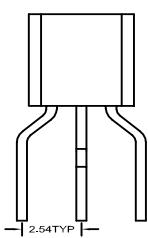
SOT54  
Bulk Pack - 412



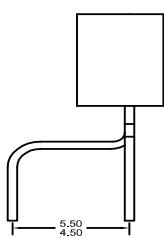
SOT54 LEADS ON CIRCLE  
Bulk Pack - 112



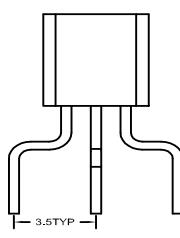
SOT54 WIDE PITCH  
Tape/ Reel Pack - 116  
Ammo Pack - 126



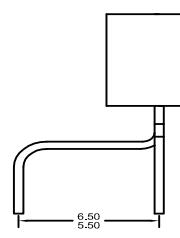
SOT54 LEAD BEND L01  
Bulk Pack - 412



5.50  
4.50



SOT54 LEAD BEND L02  
Bulk Pack - 412



6.50  
5.50

Remark: Detailed dimensions refer to POD drawing.

**Fig. 12. Package outline TO-92 (SOT54)**

### IMPORTANT NOTICE – PLEASE READ CAREFULLY

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